Triacs BT138 series

GENERAL DESCRIPTION

Passivated triacs in a plastic envelope, intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

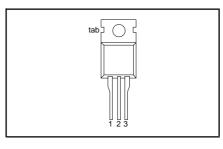
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
	BT138- BT138- BT138-	600 600F 600G	800 800F 800G	
V_{DRM}	Repetitive peak off-state	600	800	V
I _{T(RMS)} I _{TSM}	voltages RMS on-state current Non-repetitive peak on-state current	12 95	12 95	A A

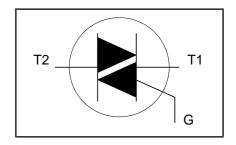
PINNING - TO220AB

PIN	DESCRIPTION				
1	main terminal 1				
2	main terminal 2				
3	gate				
tab	main terminal 2				

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER CONDITIONS		MIN.	M.A	۸X.	UNIT
V_{DRM}	Repetitive peak off-state voltages		-	-600 600 ¹	-800 800	V
$I_{T(RMS)}\\I_{TSM}$	RMS on-state current Non-repetitive peak on-state current	full sine wave; $T_{mb} \le 99 ^{\circ}\text{C}$ full sine wave; $T_{j} = 25 ^{\circ}\text{C}$ prior to surge	-		2	A
		t = 20 ms	-		5	A
l ² t	I ² t for fusing	t = 16.7 ms t = 10 ms	_)5 5	A A ² s
dl _⊤ /dt	Repetitive rate of rise of on-state current after	$I_{TM} = 20 \text{ A}; I_G = 0.2 \text{ A}; \\ dI_G/dt = 0.2 \text{ A}/\mu\text{s}$				
	triggering	T2+ G+	-		0	A/μs
		T2+ G- T2- G-	-		0 0	A/μs
		T2- G- T2- G+	_		0	A/μs A/μs
I _{GM}	Peak gate current		-			À
V_{GM}	Peak gate voltage		-		<u>2</u> 5	V
P _{GM}	Peak gate power	over any 20 ms period	-			W W
$\begin{bmatrix} P_{G(AV)} \\ T_{stg} \\ T_j \end{bmatrix}$	Average gate power Storage temperature Operating junction	over any 20 ms period	-40 -	15	.5 50 25	,C ,C
	temperature					

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 $A/\mu s$.

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	full cycle half cycle in free air		- - 60	1.5 2.0 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.		MAX.		UNIT
		BT138-				F	G	
I _{GT}	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$		_	25	٥.	F0	A
		T2+ G+ T2+ G-	_	5 8	35 35	25 25	50 50	mA mA
		T2- G-	_	10	35	25	50 50	mA
		T2- G+	-	22	70	70	100	mA
I _L	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$						
		T2+ G+	-	7	40	40	60	mA
		T2+ G-	-	20	60	60	90	mA
		T2- G- T2- G+	_	8 10	40 60	40 60	60 90	mA mA
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	6	30	30	60	mA
V_{T}	On-state voltage	I _⊤ = 15 A	_	1.4		1.65] v
V _{GT}	Gate trigger voltage	$\dot{V}_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$	-	0.7		1.5		V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A};$	0.25	0.4		-		V
I _D	Off-state leakage current	$T_{i} = 125 ^{\circ}\text{C}$ $V_{D} = V_{DRM(max)};$ $T_{i} = 125 ^{\circ}\text{C}$	-	0.1		0.5		mA

DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	BT138- $V_{DM} = 67\% V_{DRM(max)};$ $T_i = 125 °C;$ exponential	 100	F 50	G 200	250	-	V/μs
dV _{com} /dt	Critical rate of change of commutating voltage	waveform; gate open circuit $V_{DM} = 400 \text{ V}; T_j = 95 ^{\circ}\text{C};$ $I_{T(RMS)} = 12 \text{ A};$ $dI_{com}/dt = 5.4 \text{ A/ms}; gate$	-	-	10	20	-	V/μs
\mathbf{t}_{gt}	Gate controlled turn-on time	open circuit $I_{TM} = 16 \text{ A}$; $V_D = V_{DRM(max)}$; $I_G = 0.1 \text{ A}$; $dI_G/dt = 5 \text{ A}/\mu \text{s}$	-	-	-	2	-	μs

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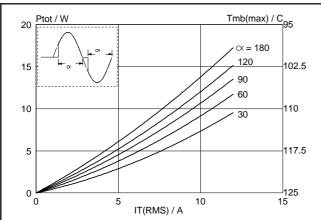


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where $\alpha =$ conduction angle.

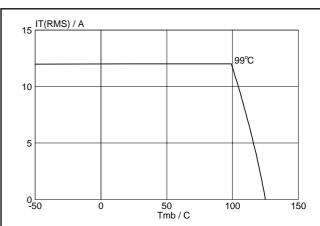


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

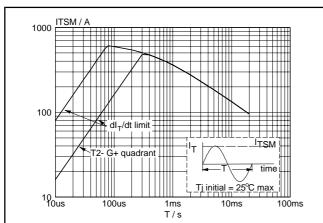


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

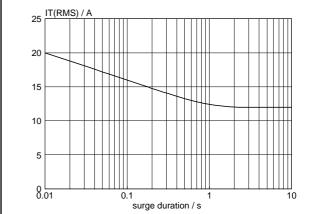


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \le 99$ °C.

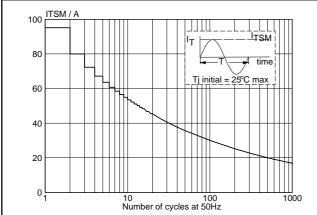


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

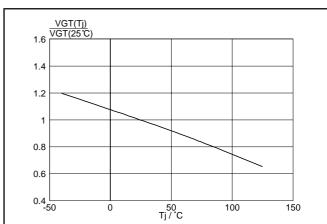
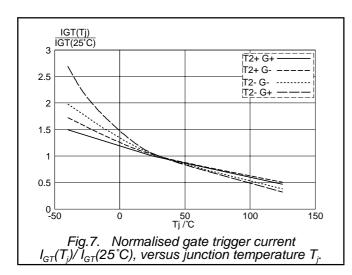


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_{j} .

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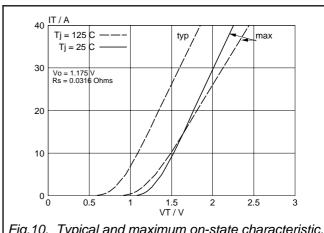
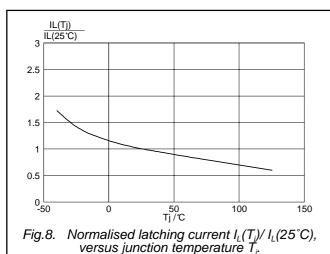


Fig. 10. Typical and maximum on-state characteristic.



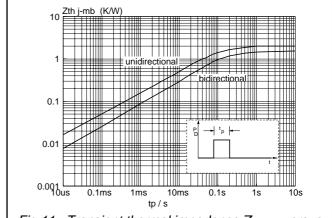


Fig.11. Transient thermal impedance $Z_{th j-mb}$, versus pulse width $t_{\rm p}$

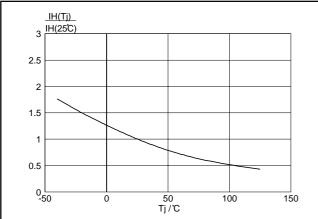


Fig.9. Normalised holding current $I_H(T_i)/I_H(25^{\circ}\text{C})$, versus junction temperature T_j .

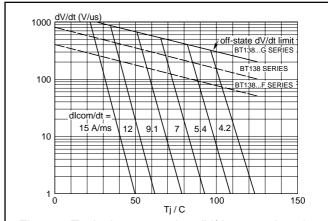
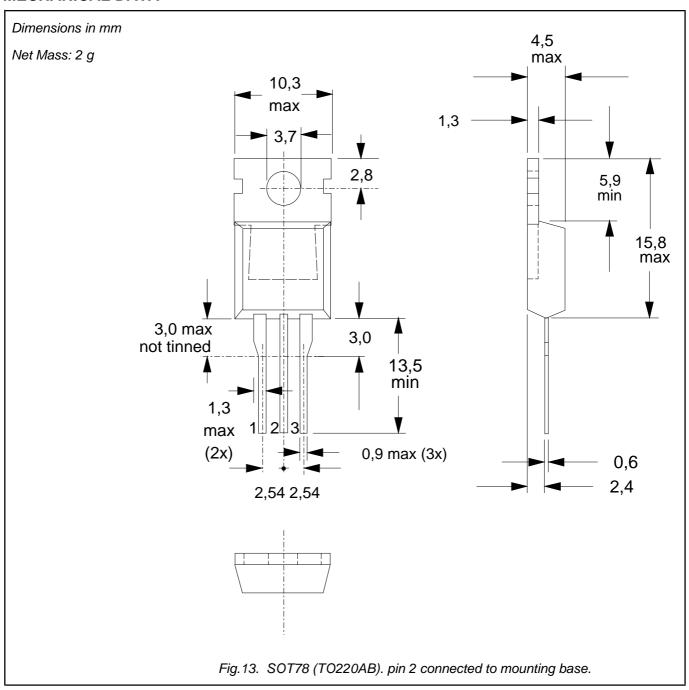


Fig.12. Typical commutation dV/dt versus junction temperature, parameter commutation dl_T/dt. The triac should commutate when the dV/dt is below the value on the appropriate curve for pre-commutation dI_{τ}/dt .

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MECHANICAL DATA



- Notes
 1. Refer to mounting instructions for SOT78 (TO220) envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

DATA SHEET STATUS						
DATA SHEET STATUS ²	PRODUCT STATUS ³	DEFINITIONS				
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice				
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product				
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A				

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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